

ET2854

Conductor

Description

ET2854 is a nickel plateable silver end termination designed to be compatible on Multilayer ceramic chips especially on alumina bodies. Nickel plating can be done without pre-plate processing due to the low glass content on the fired surface.

Key Features

- Excellent adhesion property after plating Excellent hermeticity



This picture does not show the packaging of ET2854 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Viscosity	40-50 Pas brookfield HBDV-III ultra SC4- 14 spindle and 6R utility cup at 10 rpm, 25 °C
Solids	76-80%
Alloy Ratio	100
Metal	Ag

Recommended Processing Guide

Drying Temperature	150 °C for 8 minutes Peak temp: 175 °C
Process Temperature (TDS)	630- 800°C peak temperature Dwell time of 5 – 7 minutes
Recommended Thinner	Heraeus SRV-372

ET2854

Conductor

Warranty

6 months

Storage

Store in a dry location at 5 – 25 °C

Americas

Phone +1 610 825 6050

electronics.americas@heraeus.com

Asia Pacific

Phone +65 6571 7649

electronics.apac@heraeus.com

China

Phone +86 53 5815 9601

electronics.china@heraeus.com

Europe, Middle East and Africa

Phone +49 6181 35 4370

electronics.emea@heraeus.com

The descriptions and engineering data shown here have been compiled by Heraeus using commonly accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for particular application. The Heraeus logo and Heraeus, figurative mark are trademarks or registered trademarks of Heraeus Holding GmbH or its affiliates. All rights reserved.

All changes are based on information displayed using the template `data_sheet/HET/TFM/print_data_sheet.html.twig`.
Version (last updated) 26 Feb 2026

Heraeus Electronics GmbH & Co.KG, 63450 Hanau, Germany
Web: www.heraeus-electronics.com